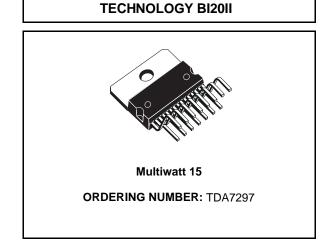


15+15W DUAL BRIDGE AMPLIFIER

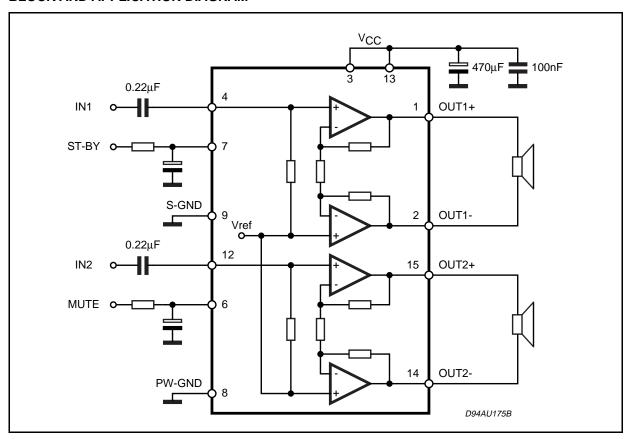
- WIDE SUPPLY VOLTAGE RANGE (6V -18V)
- MINIMUM EXTERNAL COMPONENTS
 - NO SWR CAPACITOR
 - NO BOOTSTRAP
 - NO BOUCHEROT CELLS
 - INTERNALLY FIXED GAIN
- STAND-BY & MUTE FUNCTIONS
- SHORT CIRCUIT PROTECTION
- THERMAL OVERLOAD PROTECTION



DESCRIPTION

The TDA7297 is a dual bridge amplifier specially designed for TV and Portable Radio applications.

BLOCK AND APPLICATION DIAGRAM



July 2002 1/9

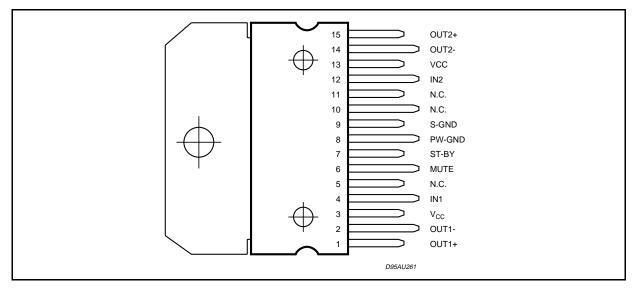
ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
Vs	Supply Voltage	20	V
Io	Output Peak Current (internally limited)	2	Α
P _{tot}	Total Power Dissipation (T _{case} = 70°C)	33	W
Top	Operating Temperature	0 to 70	°C
T _{stg} , T _j	Storage and Junction Temperature	-40 to +150	°C

THERMAL DATA

Symbol	Description	Value		Unit
R _{th j-case}	Thermal Resistance Junction to case	Typ. 1.4	Max. 2	°C/W

PIN CONNECTION (Top view)



ELECTRICAL CHARACTERISTICS (V_{CC} = 16.5V, R_L = 8Ω , f = 1kHz, T_{amb} = 25°C unless otherwise specified.)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
V _{CC}	Supply Range		6.5		18	V
Ιq	Total Quiescent Current	R _L = ∞		50	65	mA
Vos	Output Offset Voltage				120	mV
Po	Output Power	THD = 10%	13	15		W
THD	Total Harmonic Distortion	$P_O = 1W$		0.1	0.3	%
		$P_0 = 0.1W \text{ to } 5W$ f = 100Hz to 15kHz			1	%
SVR	Supply Voltage Rejection	f = 100Hz V _R = 0.5V	40	56		dB
CT	Crosstalk		46	60		dB
A _{MUTE}	Mute Attenuation		60	80		dB
T_W	Thermal Threshold			150		°C
G∨	Closed Loop Voltage Gain		31	32	33	dB
ΔGv	Voltage Gain Matching				0.5	dB
Ri	Input Resistance		25	30		ΚΩ

ELECTRICAL CHARACTERISTICS (Continued)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
VT _{MUTE}	Mute Threshold	$V_O = -30$ dB	2.3	2.9	4.1	V
VT _{ST-BY}	St-by Threshold		0.8	1.3	1.8	V
I _{ST-BY}	ST-BY current V6 = GND				100	μΑ
e _N	Total Output Noise Voltage	A curve f = 20Hz to 20kHz		150 220	500	μV μV

APPLICATION SUGGESTION

STAND-BY AND MUTE FUNCTIONS

(A) Microprocessor Application

In order to avoid annoying "Pop-Noise" during Turn-On/Off transients, it is necessary to guarantee the right St-by and mute signals sequence. It is quite simple to obtain this function using a microprocessor (Fig. 1 and 2).

At first St-by signal (from mP) goes high and the voltage across the St-by terminal (Pin 7) starts to increase exponentially. The external RC network is intended to turn-on slowly the biasing circuits of

the amplifier, this to avoid "POP" and "CLICK" on the outputs.

When this voltage reaches the St-by threshold level, the amplifier is switched-on and the external capacitors in series to the input terminals (C3, C5) start to charge.

It's necessary to mantain the mute signal low until the capacitors are fully charged, this to avoid that the device goes in play mode causing a loud "Pop Noise" on the speakers.

A delay of 100-200ms between St-by and mute signals is suitable for a proper operation.

Figure 1: Microprocessor Application

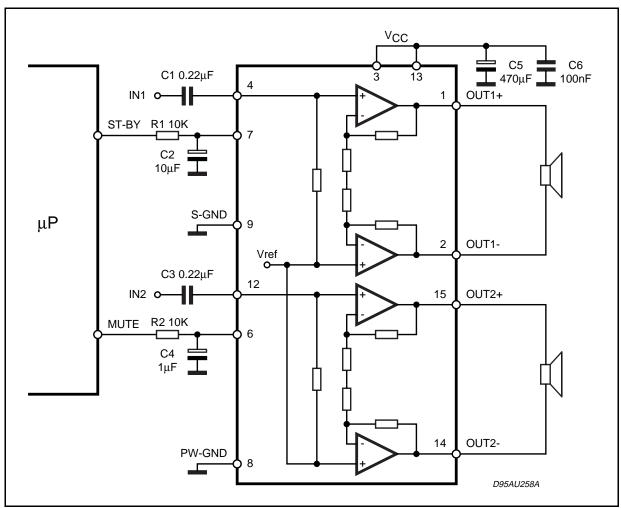
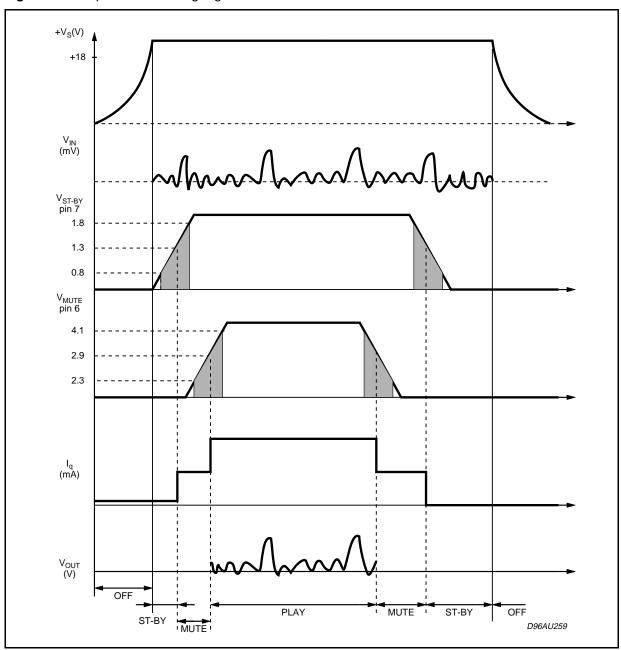


Figure 2: Microprocessor Driving Signals.



(B) Low Cost Application

The St-by and mute terminals are tied together and they are connected to the supply line via an

external voltage divider.

The device is switched-on/off from the supply line and the external capacitor C4 is intended to delay the St-by and mute threshold exceeding, avoiding "Popping" problems.

Figure 3: Stand-alone Low-cost Application.

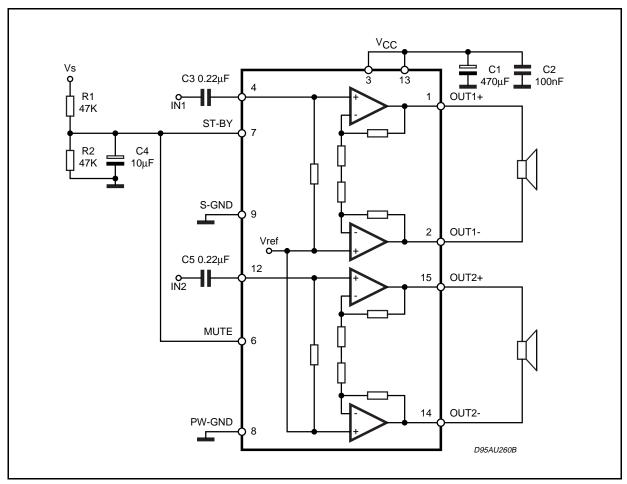


Figure 3b: PCB and Component Layout of the Application Circuit (Fig. 1).

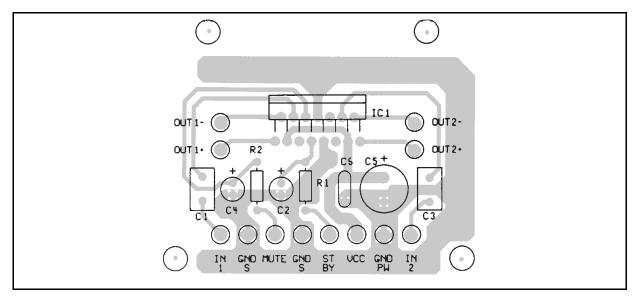


Figure 4: Distortion vs Output Power

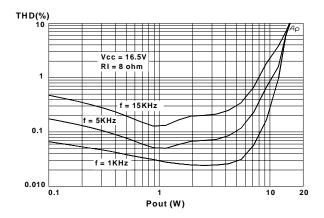


Figure 5: Distortion vs Output Power

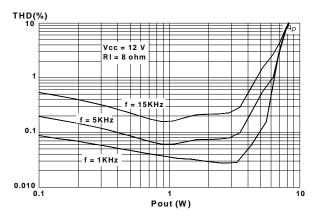


Figure 6: Distortion vs Frequency

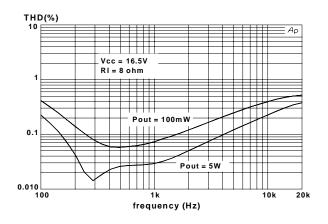


Figure 7: Frequency Respone

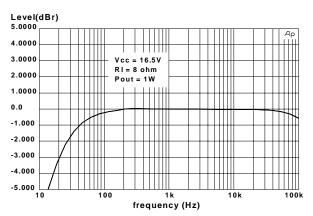


Figure 8: Output Power vs Supply Voltage

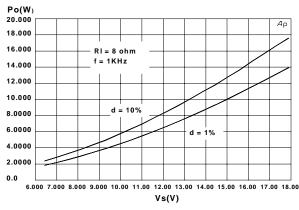


Figure 9: Total Power Dissipation & Efficiency vs Output Power

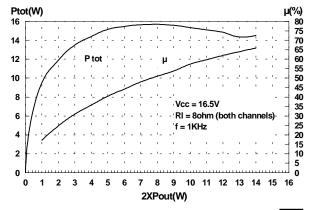


Figure 10: Mute Attenuation vs. V pin.6

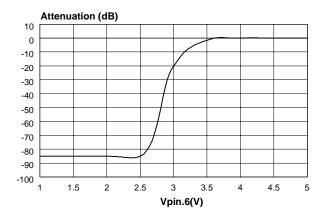


Figure 11: Stand-By Attenuation vs Vpin.7

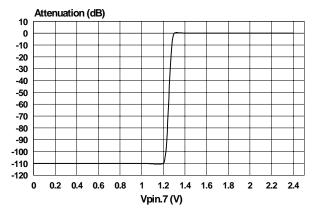
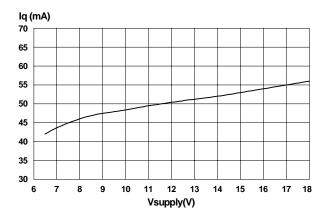
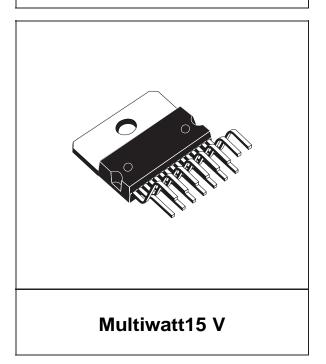


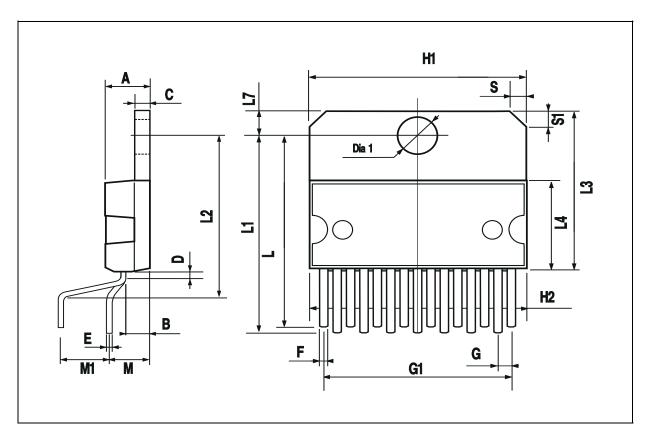
Figure 12: Quiscent Current vs. Supply Voltage



DIM.		mm	mm inch			
DIN.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α			5			0.197
В			2.65			0.104
С			1.6			0.063
D		1			0.039	
Е	0.49		0.55	0.019		0.022
F	0.66		0.75	0.026		0.030
G	1.02	1.27	1.52	0.040	0.050	0.060
G1	17.53	17.78	18.03	0.690	0.700	0.710
H1	19.6			0.772		
H2			20.2			0.795
L	21.9	22.2	22.5	0.862	0.874	0.886
L1	21.7	22.1	22.5	0.854	0.870	0.886
L2	17.65		18.1	0.695		0.713
L3	17.25	17.5	17.75	0.679	0.689	0.699
L4	10.3	10.7	10.9	0.406	0.421	0.429
L7	2.65		2.9	0.104		0.114
М	4.25	4.55	4.85	0.167	0.179	0.191
M1	4.63	5.08	5.53	0.182	0.200	0.218
S	1.9		2.6	0.075		0.102
S1	1.9		2.6	0.075		0.102
Dia1	3.65		3.85	0.144		0.152

OUTLINE AND MECHANICAL DATA





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